

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of) Attorney Docket No.: **MIYOSH0006**
Kazuyoshi TENDOU et al.)
Serial No.: 10/596,387) Confirmation No.: 5987
Filed: April 13, 2007) Group Art Unit: 1796
For: EPOXY RESIN MOLDING) Examiner: Michael J. FEELY
MATERIAL FOR SEALING AND)
ELECTRONIC COMPONENT) Date: September 16, 2009

AMENDMENT (B)

MAIL STOP: AMENDMENT
U.S. Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In response to the non-final Office Action mailed June 22, 2009, please amend the application identified above as follows:

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.